

WHAT IS CLAIMED IS:

1. A semiconductor package for removing flash from a portion of a semiconductor package to be plated before a plating process and after a sealing process accompanied by resin molding during the manufacture of semiconductors comprising:

grooves formed at side flash attached to corner regions between sealing units and lead units as regions where it is difficult to perform a deflashing process after the sealing process, in particular, at a portion of the side flash located at adjacent positions to the sealing units.

2. A method for forming grooves at a semiconductor package in order to remove flash from a portion of the semiconductor package to be plated before a plating process and after a sealing process accompanied by resin molding during the manufacture of semiconductors, comprising the step of:

a) forming grooves at side flash attached to corner regions between sealing units and lead units as regions where it is difficult to perform a deflashing process, in particular, at a portion of the side flash located at adjacent positions to the sealing units, by laser irradiation,

wherein the grooves are formed by irradiating laser beams at a fixed position while feeding the semiconductor package.

3. The method as set forth in claim 2, wherein the grooves are formed by irradiating the laser beams while changing irradiation directions in a state wherein the semiconductor package is fixed.

4. The method as set forth in claim 2, wherein the grooves are formed by irradiating the laser beams onto one side of the semiconductor package.

5. The method as set forth in claim 2, wherein the grooves are formed by irradiating the laser beams onto both sides of the semiconductor package so that the laser beams irradiated onto both sides of the semiconductor package are alternate to each other, as opposed to than facing each other.

6. A deflashing method using a semiconductor package formed with grooves for removing flash from a portion of the semiconductor to be plated before a plating process and after a sealing process accompanied by resin molding during the manufacture of semiconductors comprising the step of:

a) removing side flash, remaining after the grooves are formed at the side flash located at regions where it is difficult to perform a deflashing process, and being maintained in an easily removable state due to the grooves, by injecting

water jet or other media.